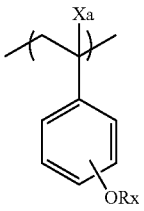
(III)



in which

Xa represents a hydrogen atom or a linear or branched alkyl group, and

Rx represents a hydrogen atom or a group that when acted on by an acid, is decomposed to thereby be cleaved.

6. The method according to claim **1**, wherein the resin (A) contains neither any aromatic group containing a phenolic hydroxyl group nor any aromatic group containing a phenolic hydroxyl group whose hydrogen atom is replaced by a group that when acted on by an acid, is decomposed to thereby be cleaved.

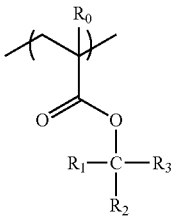
7. The method according to claim **1**, wherein the developer is a developer comprising at least one organic solvent selected from among a ketone solvent, an ester solvent, an alcohol solvent, an amide solvent and an ether solvent.

8. An actinic-ray- or radiation-sensitive resin composition for use in the method according to claim **1**.

9. The actinic-ray- or radiation-sensitive resin composition according to claim **8**, comprising a resin (A) comprising a repeating unit containing a group that when acted on by an acid, is decomposed to thereby produce a polar group and comprising an aromatic group, which resin when acted on by an acid, decreases its solubility in an organic solvent, a non-ionic compound (B) that when exposed to actinic rays or radiation, generates an acid and a solvent (C).

10. The actinic-ray- or radiation-sensitive resin composition according to claim **8**, wherein the repeating unit containing a group that when acted on by an acid, is decomposed to thereby produce a polar group, contained in the resin (A) is expressed by general formula (I) below,

(I)



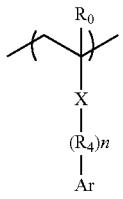
in which

R_0 represents a hydrogen atom or a linear or branched alkyl group optionally substituted with a fluorine atom or a hydroxyl group, and

each of R_1, R_2 and R_3 independently represents an optionally substituted linear or branched alkyl group or an optionally substituted cycloalkyl group, provided that any two of R_1, R_2 and R_3 may be bonded to each other to thereby form a monocyclic or polycyclic structure.

11. The actinic-ray- or radiation-sensitive resin composition according to claim **8**, wherein a repeating unit containing the aromatic group contained in the resin (A) is expressed by general formula (II) below,

(II)



in which

R_0 represents a hydrogen atom or a linear or branched alkyl group optionally substituted with a fluorine atom or a hydroxyl group,

X represents a single bond or a bivalent connecting group,

Ar represents an optionally substituted aromatic group, provided that when a substituent is introduced in the aromatic group, the substituent is any of an alkyl group (optionally substituted), a cycloalkyl group (optionally substituted), an aryl group, a halogen atom, a cyano group, an amino group, a nitro group and a carboxyl group,

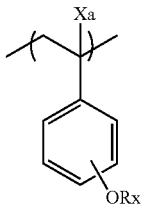
R_4 represents an optionally substituted alkylene group, and

n is an integer of 0 to 4.

12. The actinic-ray- or radiation-sensitive resin composition according to claim **11**, wherein in general formula (II), X is —COO— or —CONH—.

13. The actinic-ray- or radiation-sensitive resin composition according to claim **8**, wherein the content of any of repeating units of general formula (III) below contained in the resin (A) is up to 20 mol % based on all the repeating units of the resin (A),

(III)



in which

Xa represents a hydrogen atom or a linear or branched alkyl group, and

Rx represents a hydrogen atom or a group that when acted on by an acid, is decomposed to thereby be cleaved.

14. The actinic-ray- or radiation-sensitive resin composition according to claim **8**, wherein the resin (A) contains neither any aromatic group containing a phenolic hydroxyl group nor any aromatic group containing a phenolic hydroxyl group whose hydrogen atom is replaced by a group that when acted on by an acid, is decomposed to thereby be cleaved.

15. An actinic-ray- or radiation-sensitive film formed from the actinic-ray- or radiation-sensitive resin composition according to claim **8**.

16. A process for manufacturing a semiconductor device, comprising the method according to claim **1**.

17. A semiconductor device manufactured by the process of claim **16**.

18. The actinic-ray- or radiation-sensitive resin composition according to claim **11**, wherein X represents a single bond and/or n is an integer of 1 to 4.

* * * * *